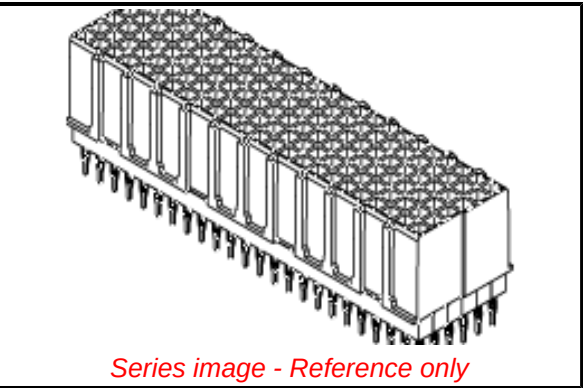


PLEASE CHECK WWW.MOLEX.COM FOR LATEST PART INFORMATION

Part Number: [0737801147](#)
Status: **Active**
Overview: [HDM Backplane Connector System](#)
Description: HDM Board-to-Board Daughtercard Receptacle, Vertical, Signal Module, 144 Circuits, Mounted Height 17.00mm, Pin Length 3.00mm, Solder Tail



Documents:
[Drawing \(PDF\)](#) [Packaging Specification PK-70873-0872-001 \(PDF\)](#)
[Product Specification PS-73780-999-001 \(PDF\)](#) [RoHS Certificate of Compliance \(PDF\)](#)

Agency Certification
UL E29179

General
Product Family Backplane Connectors
Series [73780](#)
Application Daughtercard, Mezzanine
Comments Solder Tail
Component Type PCB Receptacle
Overview [HDM Backplane Connector System](#)
Product Name HDM
UPC 800754870665

Physical
Circuits (Loaded) 144
Circuits (maximum) 144
Color - Resin Black
Durability (mating cycles max) 250
First Mate / Last Break No
Flammability 94V-0
Guide to Mating Part No
Keying to Mating Part None
Material - Metal Copper-Nickel-Tin
Material - Plating Mating Gold
Material - Plating Termination Tin
Material - Resin High Temperature Thermoplastic
Net Weight 20.030/g
Number of Columns 24
Number of Pairs Open Pin Field
Number of Rows 6
Orientation Vertical
PC Tail Length 3.00mm
PCB Locator No
PCB Retention None
PCB Thickness - Recommended 1.60mm
Packaging Type Tube
Pitch - Mating Interface 2.00mm
Pitch - Termination Interface 2.00mm
Plating min - Mating 0.762µm
Plating min - Termination 2.540µm
Polarized to PCB No
Stackable Yes
Surface Mount Compatible (SMC) Yes
Temperature Range - Operating -55° to +105°C
Termination Interface: Style Through Hole

Electrical

EU ELV
Not Relevant

EU RoHS	China RoHS
Compliant	
REACH SVHC	
Not Contained Per - D(2020)9139-DC (19 Jan 2021)	
Halogen-Free Status	
Low-Halogen	
For more information, please visit Contact US	
China ROHS	Green Image
ELV	Not Relevant
RoHS Phthalates	Not Contained

Search Parts in this Series
[73780](#) Series

Mates With
HDM Board-to-Board Backplane Header [73642](#) , [73643](#) , [73644](#) , [73942](#) , [73943](#) , [73944](#) , [74349](#) , [74428](#). HDM Board-to-Board Stacking Header [73769](#) , [73770](#) , [73782](#) , [73783](#) , [73771](#)

Current - Maximum per Contact	15.0A, 1.0A
Data Rate	1.0 Gbps
Real Signals (per 25mm)	75
Shielded	No
Voltage - Maximum	250V AC

Solder Process Data

Duration at Max. Process Temperature (seconds)	005
Lead-freeProcess Capability	WAVE
Max. Cycles at Max. Process Temperature	001
Process Temperature max. C	260

Material Info

Reference - Drawing Numbers

Packaging Specification	PK-70873-0872-001
Product Specification	PS-73780-999-001
Sales Drawing	SD-73780-004

This document was generated on 03/24/2021

PLEASE CHECK WWW.MOLEX.COM FOR LATEST PART INFORMATION

Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

Molex:

73780-1147